

- Green Device Available
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Advanced high cell density Trench technology

**Product Summary**



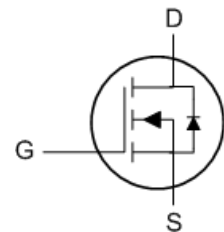
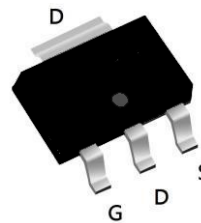
BVDSS	RDSON	ID
100V	47mΩ	6A

**Description**

The PKL0016 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The PKL0016 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

**SOT223 Pin Configuration**



**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	6	A
$I_D @ T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	4.7	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	24	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	11.3	mJ
$I_{AS}$	Avalanche Current	15	A
$P_D @ T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	1.5	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient <sup>1</sup> (Steady State)	---	70	$^\circ C/W$
	Thermal Resistance Junction-ambient <sup>1</sup> ( $t \leq 10s$ )	---	35	$^\circ C/W$

**Electrical Characteristics ( $T_J=25\text{ }^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25\text{ }^\circ\text{C}$ , $I_D=1mA$	---	0.098	---	$V/^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=5A$	---	---	47	m $\Omega$
		$V_{GS}=4.5V, I_D=5A$	---	---	50	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	---	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5.52	---	$mV/^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=80V, V_{GS}=0V, T_J=25\text{ }^\circ\text{C}$	---	---	10	$\mu A$
		$V_{DS}=80V, V_{GS}=0V, T_J=55\text{ }^\circ\text{C}$	---	---	100	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
gfs	Forward Transconductance	$V_{DS}=5V, I_D=5A$	---	6.2	---	S
$Q_g$	Total Gate Charge (10V)	$V_{DS}=80V, V_{GS}=10V, I_D=5A$	---	60	---	nC
$Q_{gs}$	Gate-Source Charge		---	9.2	---	
$Q_{gd}$	Gate-Drain Charge		---	9.9	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=50V, V_{GS}=10V, R_G=3.3\Omega$ $I_D=3A$	---	10.8	---	ns
$T_r$	Rise Time		---	27	---	
$T_{d(off)}$	Turn-Off Delay Time		---	56	---	
$T_f$	Fall Time		---	24	---	
$C_{iss}$	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1MHz$	---	3848	---	pF
$C_{oss}$	Output Capacitance		---	137	---	
$C_{riss}$	Reverse Transfer Capacitance		---	82	---	

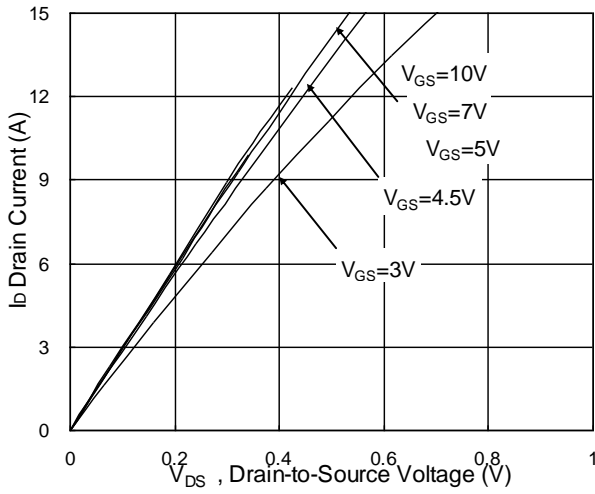
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V$ , Force Current	---	---	6	A
$I_{SM}$	Pulsed Source Current <sup>2,5</sup>		---	---	24	A
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=1A, T_J=25\text{ }^\circ\text{C}$	---	---	1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F=5A, di/dt=100A/\mu s, T_J=25\text{ }^\circ\text{C}$	---	25	---	nS
$Q_{rr}$	Reverse Recovery Charge		---	29	---	nC

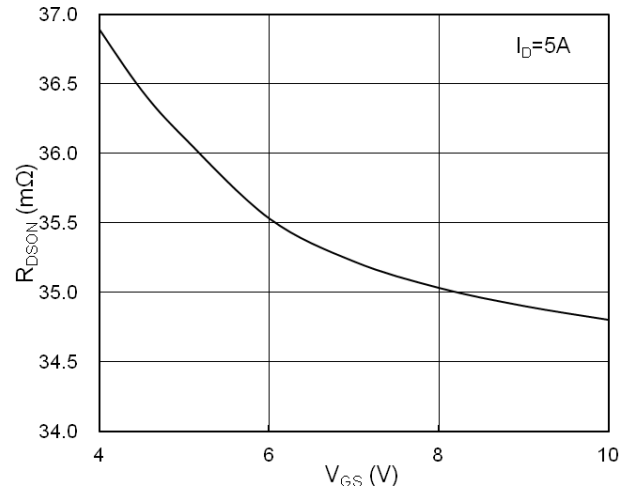
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=15A$
- 4.The power dissipation is limited by  $150\text{ }^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

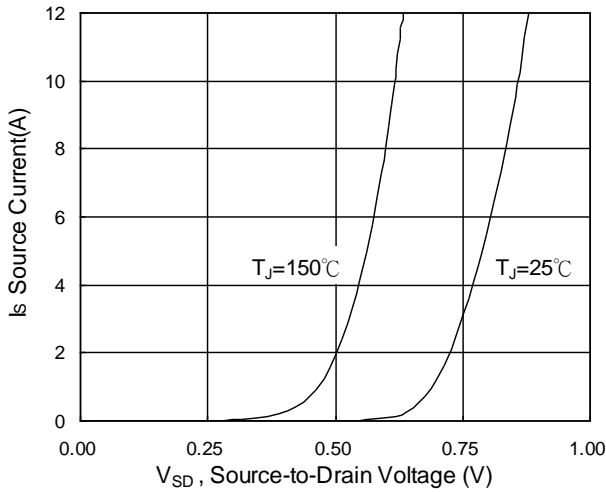
**Typical Characteristics**



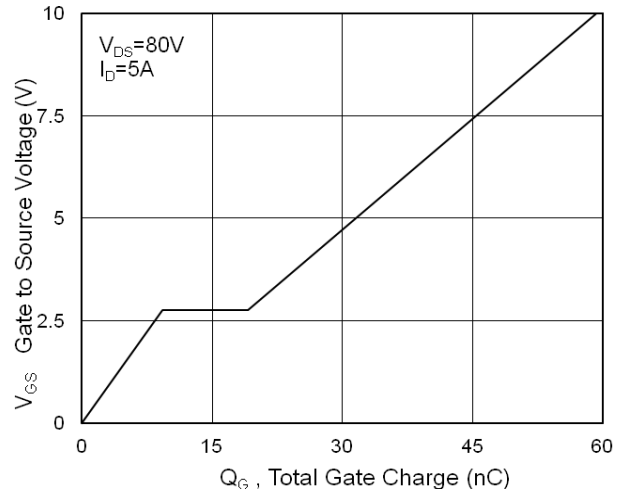
**Fig.1 Typical Output Characteristics**



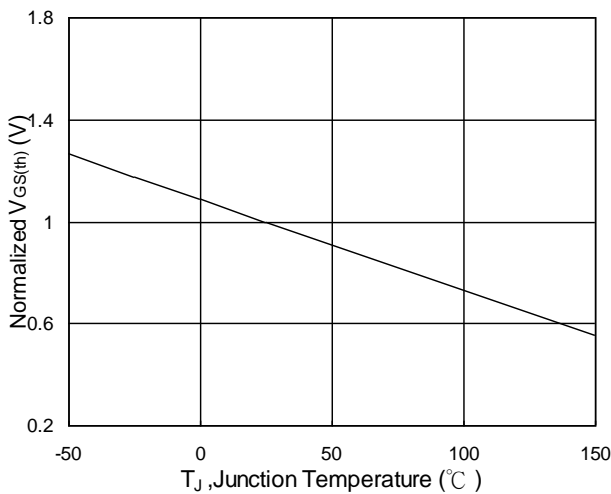
**Fig.2 On-Resistance vs. Gate-Source**



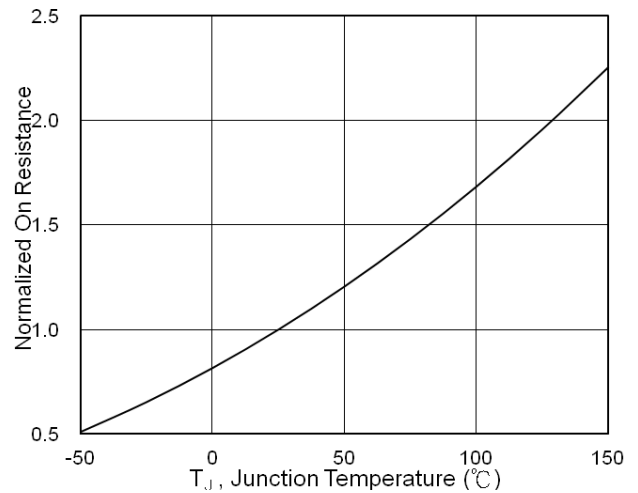
**Fig.3 Forward Characteristics Of Reverse**



**Fig.4 Gate-Charge Characteristics**

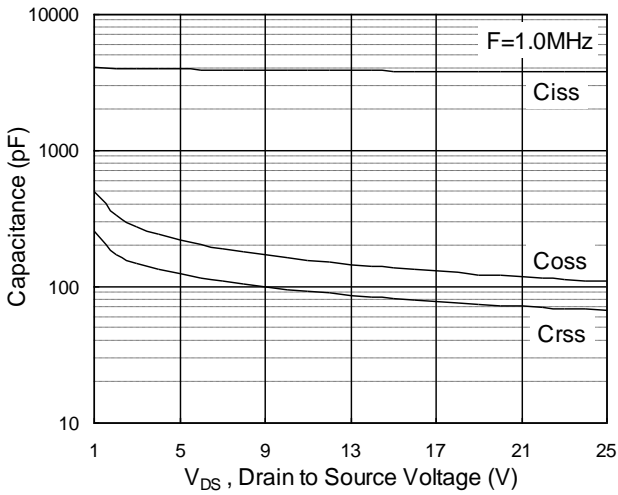


**Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$**

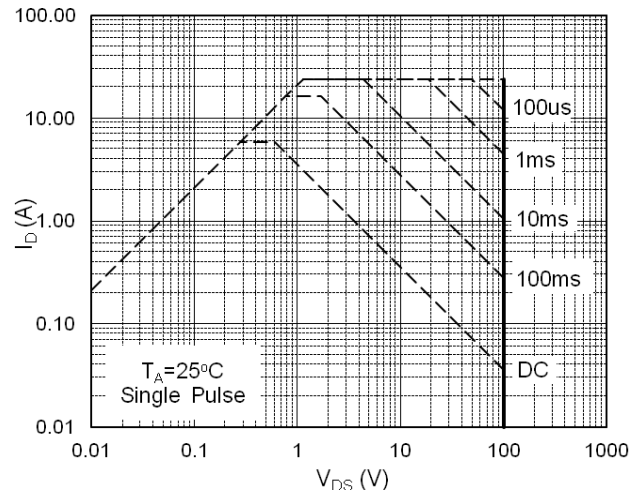


**Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$**

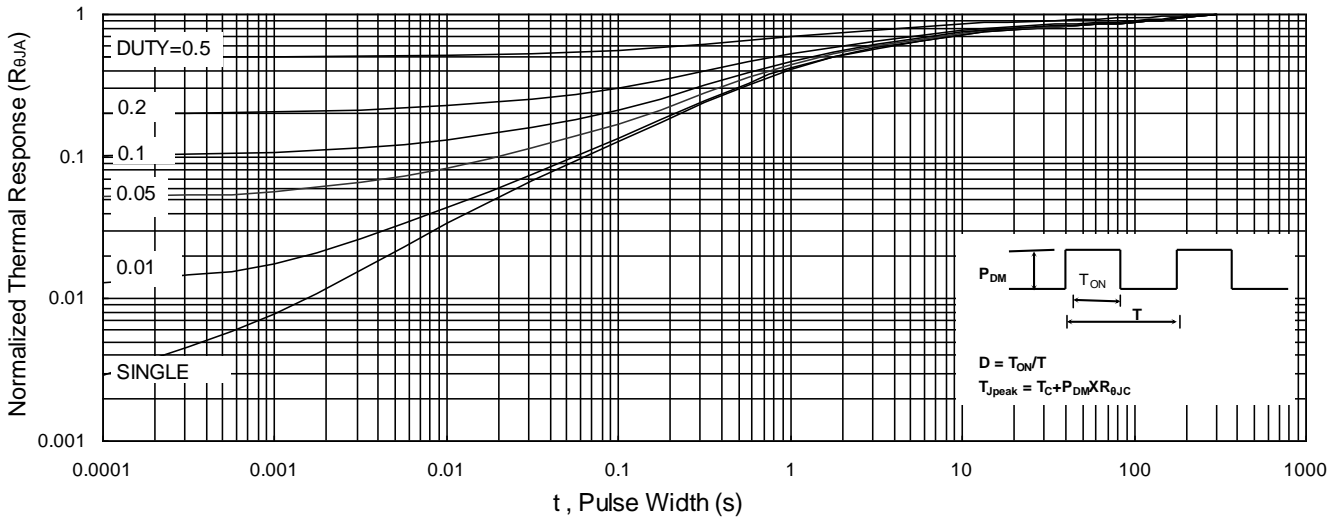
**N-Ch 100V Fast Switching MOSFETs**



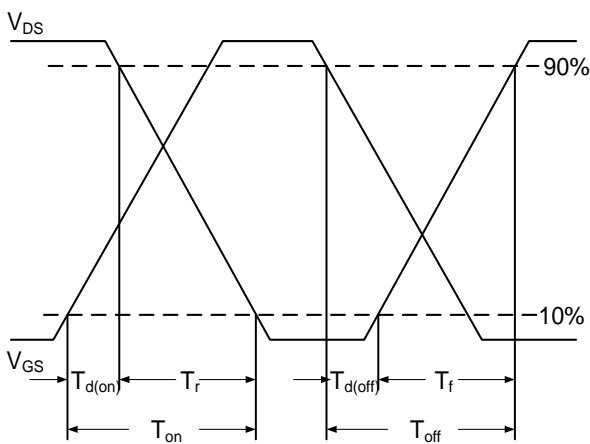
**Fig.7 Capacitance**



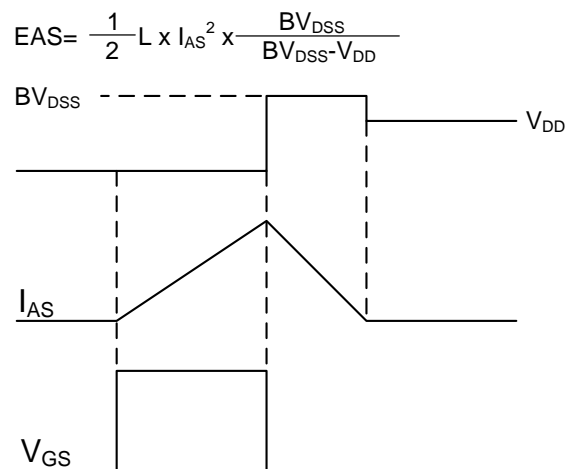
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**

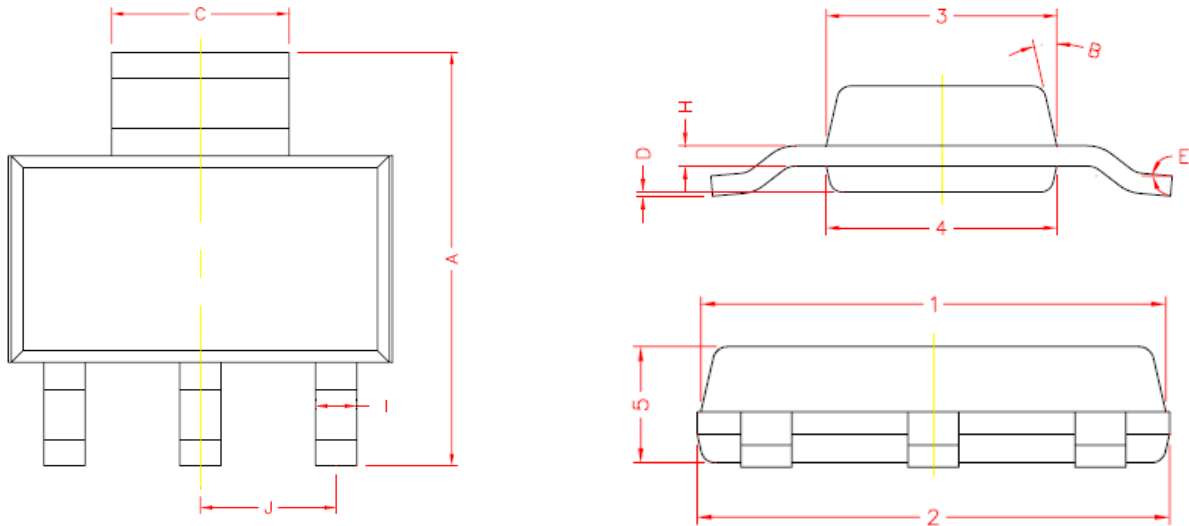


**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Switching Waveform**

**Package Information ( SOT-223 )**



REF.	DIMENSIONS	
	Millimeters	
	Min.	Max.
A	6.70	7.30
C	2.90	3.10
D	0.02	0.10
E	0°	10°
I	0.60	0.80
H	0.25	0.35
B	13° TYP.	
J	2.30 REF.	
1	6.30	6.70
2	6.30	6.70
3	3.30	3.70
4	3.30	3.70
5	1.40	1.80